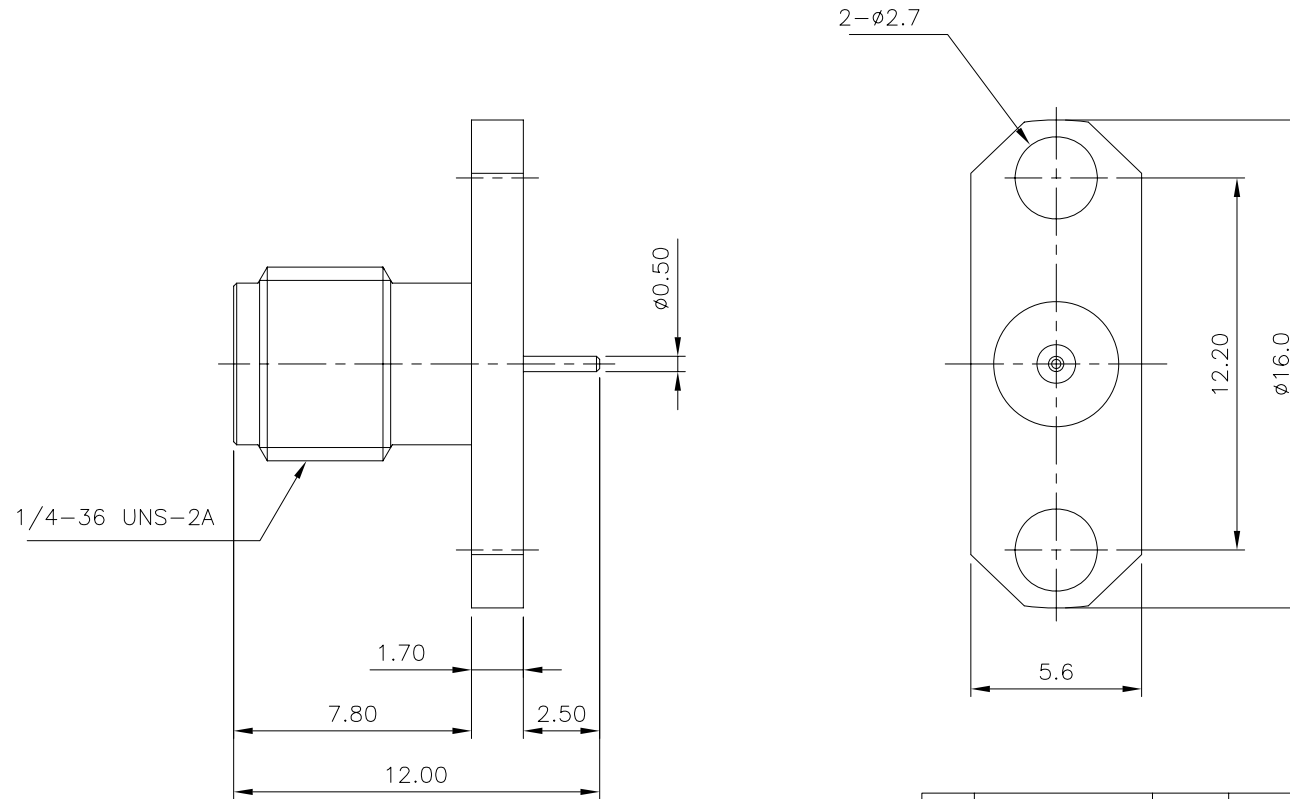


REVISION					
REV	DESCRIPTION	DRAWN	APPR	DATE	
IR	Initial Registration	M.H.SONG	I.C.KIM	2014.07.24.	
1	[설변No.201408-0004] 부적합 개선 (TEFLON 길이 상이 변경)	E.H.KIM	I.C.KIM	2014.08.19.	



3	INSULATOR	1	TEFLON		DIN00090-N/1 DIN00127-N/2
2	CONTACT	1	BeCu	Gold Plate	DCT03186-5/1
1	BODY	1	MBsBD	Gold Plate	DBD00347-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ± 0.1	DATE 2014. 08. 19.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle $\pm 1^\circ$	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY	-	TITLE SMA50 SOLDER END JS-2H
		DRAWN BY	E.H.KIM	
FINISH		SCALE	4/1	DWG NO. CN03265-7/1 REVISION 1 SHEET 1 of 1
		UNIT	mm	